

# AN12671

## Steps to migrate from M4 USB project to M0p USB example project for K32

Rev. 1 — 11 July 2022

Application note

### Document information

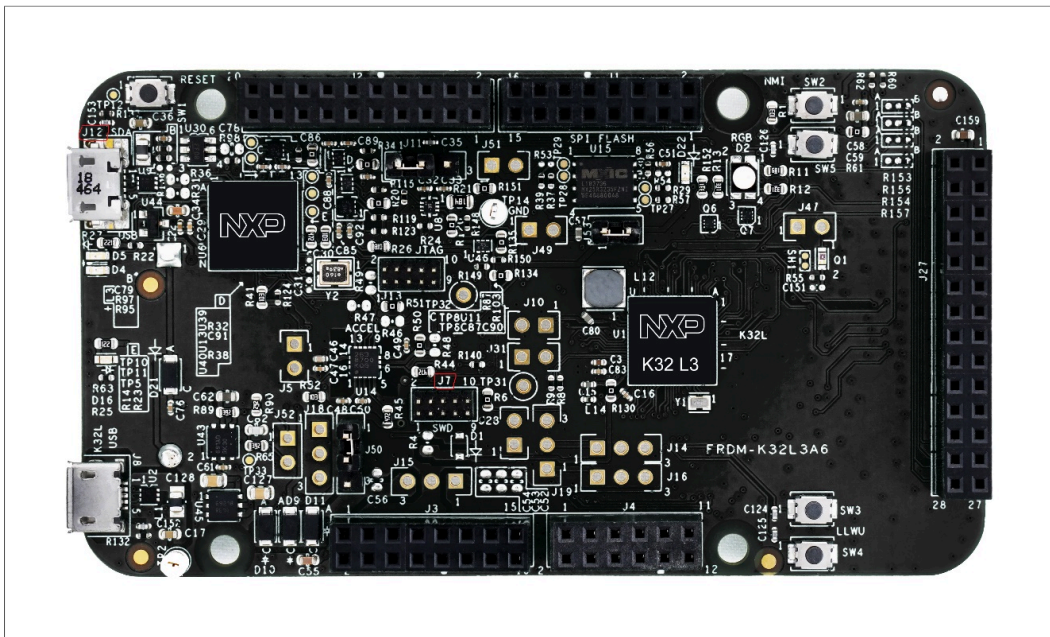
Information	Content
Keywords	AN12671, M4 USB project, M0p USB example project, K32
Abstract	This document lists the steps to migrate from M4 USB project to M0p USB example project for K32.



## 1 Introduction

MCU boots from M4 core, by default. However, it can be configured to boot from M0+ core. To do so, bit field `BOOT_CORE` in `FTFE_FOPT` register must be set to 0 (register value - `0xFFFFFBBF`).

Follow the steps below to access (program, read, erase) the `FTFE_FOPT` register using J-Link commander:



1. Connect J12 on board to PC using USB cable.
2. Connect J7 on board to PC using Jlink.
3. Open Jlink command. Once the following instructions are input, new configuration will become active after power-on-reset.

*FTFE\_FOPT value should be 0xFFFFFFFF before.*

```
w1 0x40023007 0x43 // FCCOB0: CMD_PROGRAM_ONCE (IFR)
w1 0x40023006 0x84 // FCCOB1: IFR_Index of the FOPT
w1 0x40023005 0x00 // FCCOB2: Not used
w1 0x40023004 0x00 // FCCOB3: Not used
w1 0x4002300B 0xFF // FCCOB4: Record byte 0 value --> FOPT (Bit31:Bit24)
w1 0x4002300A 0xFF // FCCOB5: Record byte 1 value --> FOPT (Bit23:Bit16)
w1 0x40023009 0xFF // FCCOB6: Record byte 2 value --> FOPT (Bit15:Bit8)
w1 0x40023008 0xBF // FCCOB7: Record byte 3 value --> FOPT (Bit7:Bit0)
w1 0x40023000 0x80 // Trigger operation
```

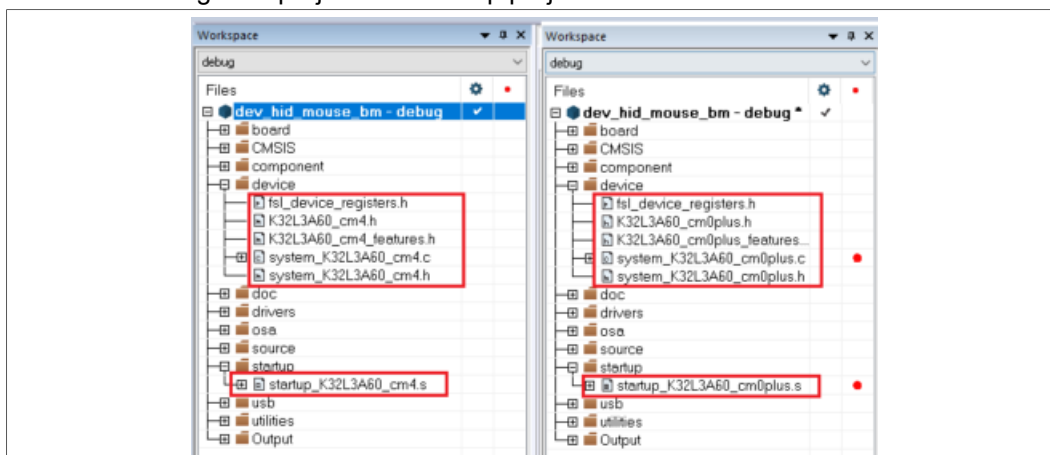
4. Additional information is available on webpage [https://wiki.segger.com/K32W#Boot\\_ROM](https://wiki.segger.com/K32W#Boot_ROM). For download issue, see the “Getting Started with MCUXpresso SDK for K32W0X2S.pdf”.

K32 has M4 and M0+ cores. USB example can run on both cores. The USB example in the release package runs on M4 core. However, this example project can be migrated from M4 to M0p core. M4 and M0p USB project use same source files with different project setting. Use the following steps to change M4 project to M0P project with IAR, MDK, and GCC compilers. Other compilers have similar way to migrate project from M4 to M0p.

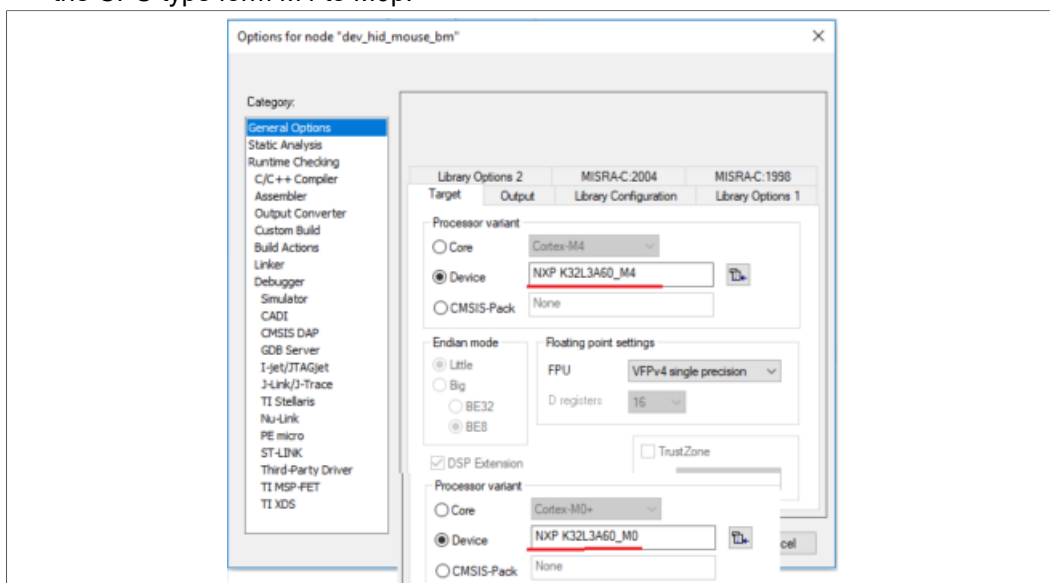
## Steps to migrate from M4 USB project to M0p USB example project for K32L

## 2 IAR

1. Update startup and system file from M4 platform files to M0p platform files. The files are available in folder: FRDM-K32L36\devices\K32L3A60. The below picture shows how to change m4 project files to M0p project file.

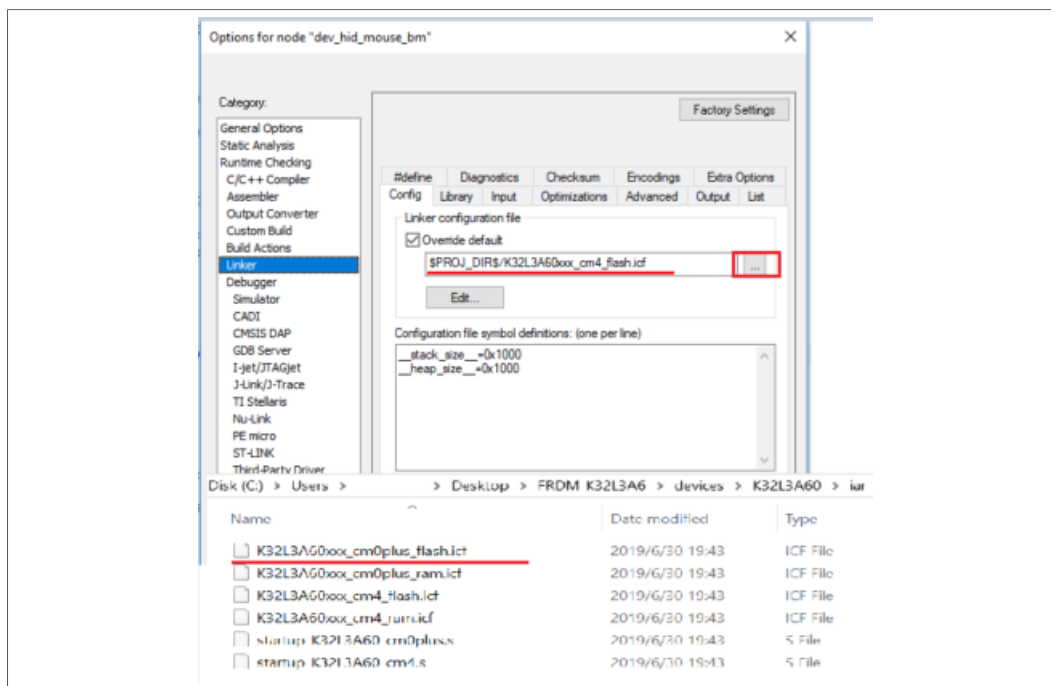


2. Open M4 project in IAR. Right click, in option-->General Options-->target and update the CPU type form M4 to M0p.

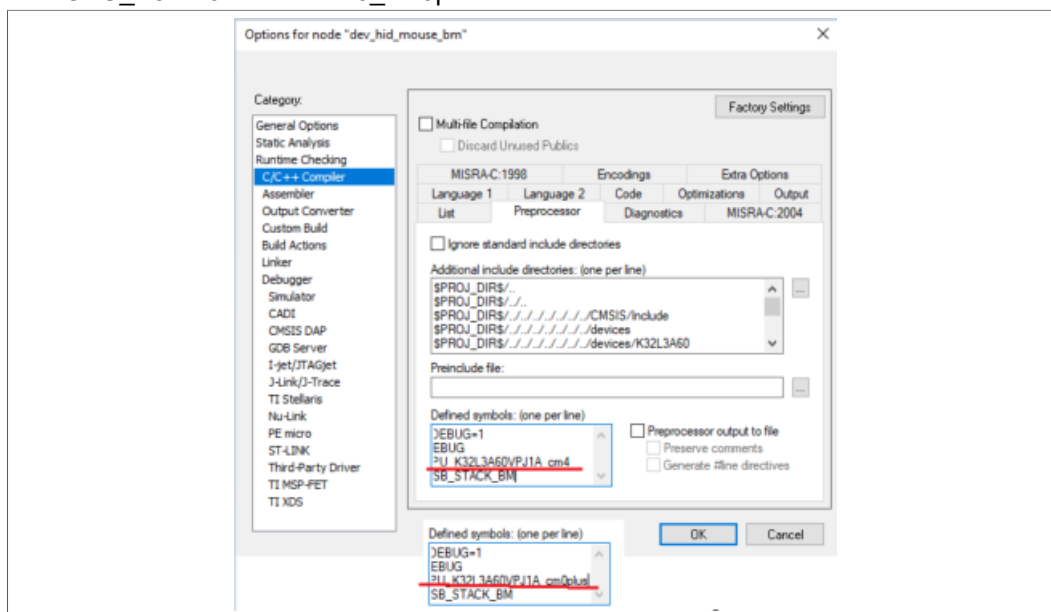


3. Again, in M4 project in IAR, in option-->linker-->config, change the linker configure file form M4 link file to M0p link file. The linker file path is devices\ K32L3A60 folder.

## Steps to migrate from M4 USB project to M0p USB example project for K32

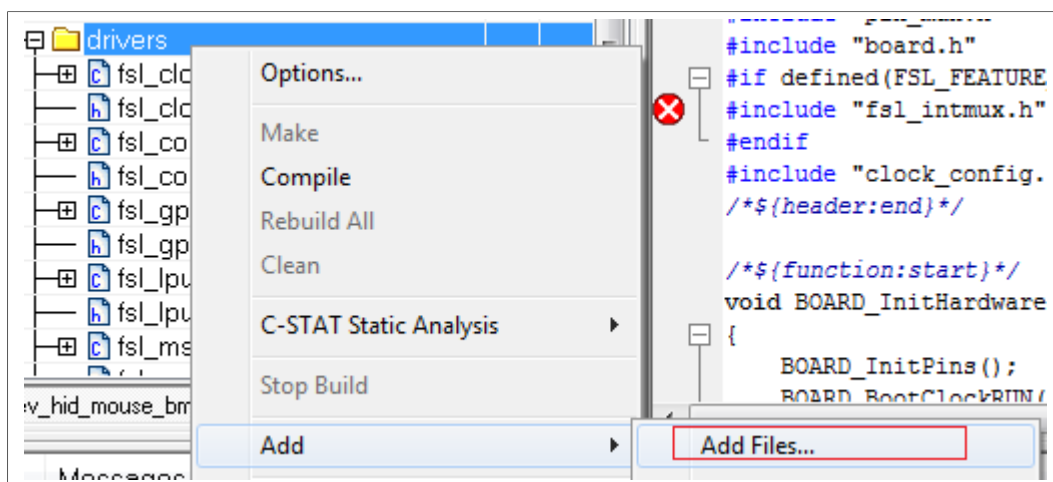


4. In M4 project in IAR, in option-->c/c++ compiler-->Preprocessor, change the CPU MACRO from "CPU\_K32W042S1M2VPJ\_cm4" to "CPU\_K32W042S1M2VPJ\_cm0plus".

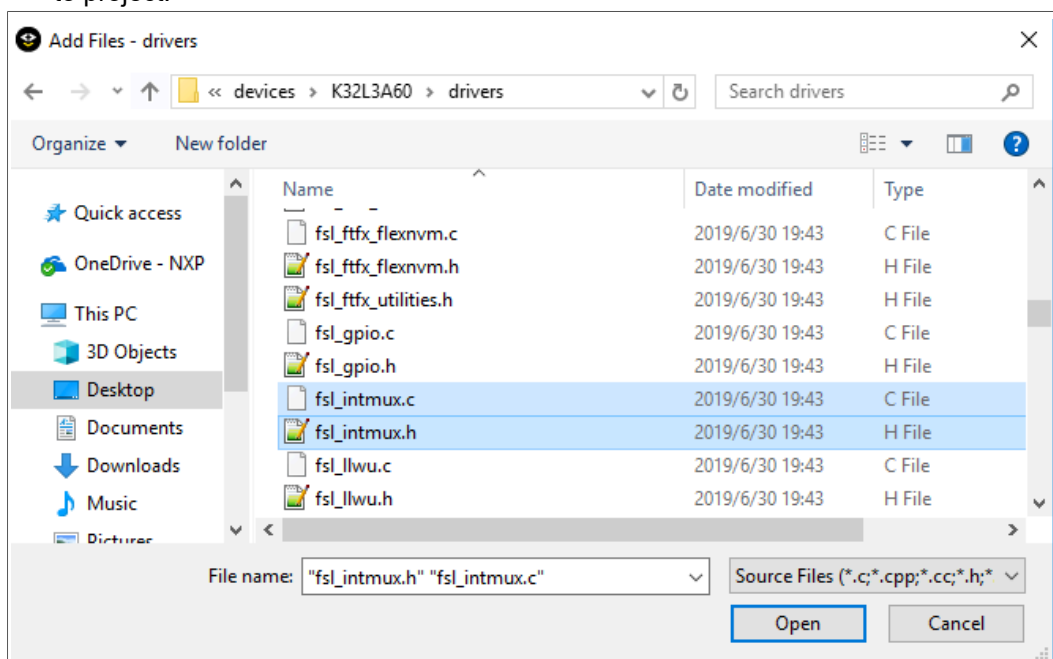


5. Add int-mux file to M0p project, driver > add > add files, as shown in the figure below

## Steps to migrate from M4 USB project to M0p USB example project for K32

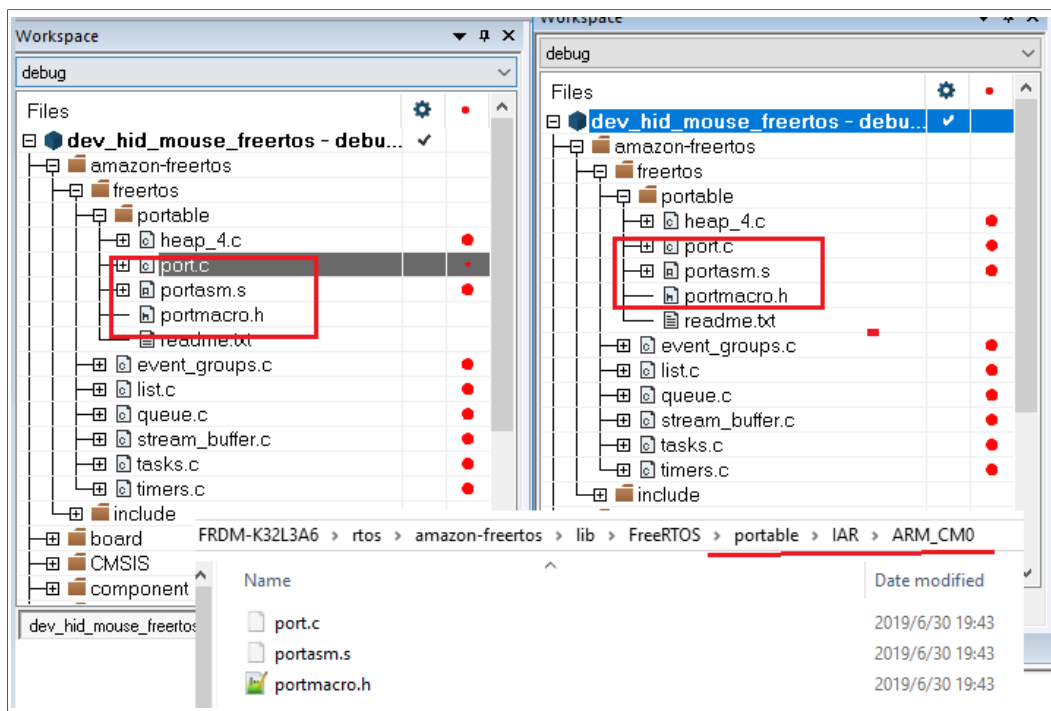


Add FRDM-K32L3A6 \devices\ K32L3A60 \drivers\fsl\_intmux.c and fsl\_intmux.h files to project.

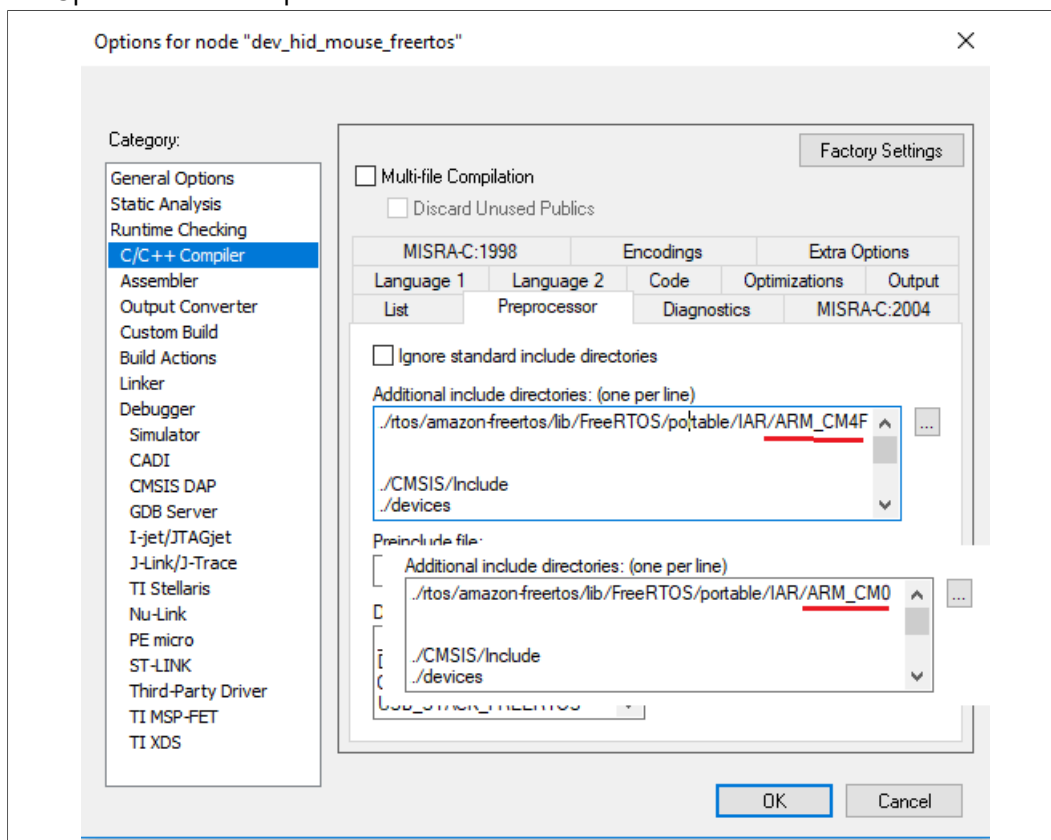


6. In M4 project in IAR, in option C/C++ compiler > Preprocessor. The file path "\$PROJ\_DIR\$/../../../../../../devices/ K32L3A60 /drivers" must be in M0p project setting.
7. For freertos example, update the freertos related portable file and include path from M4 to M0.

## Steps to migrate from M4 USB project to M0p USB example project for K32



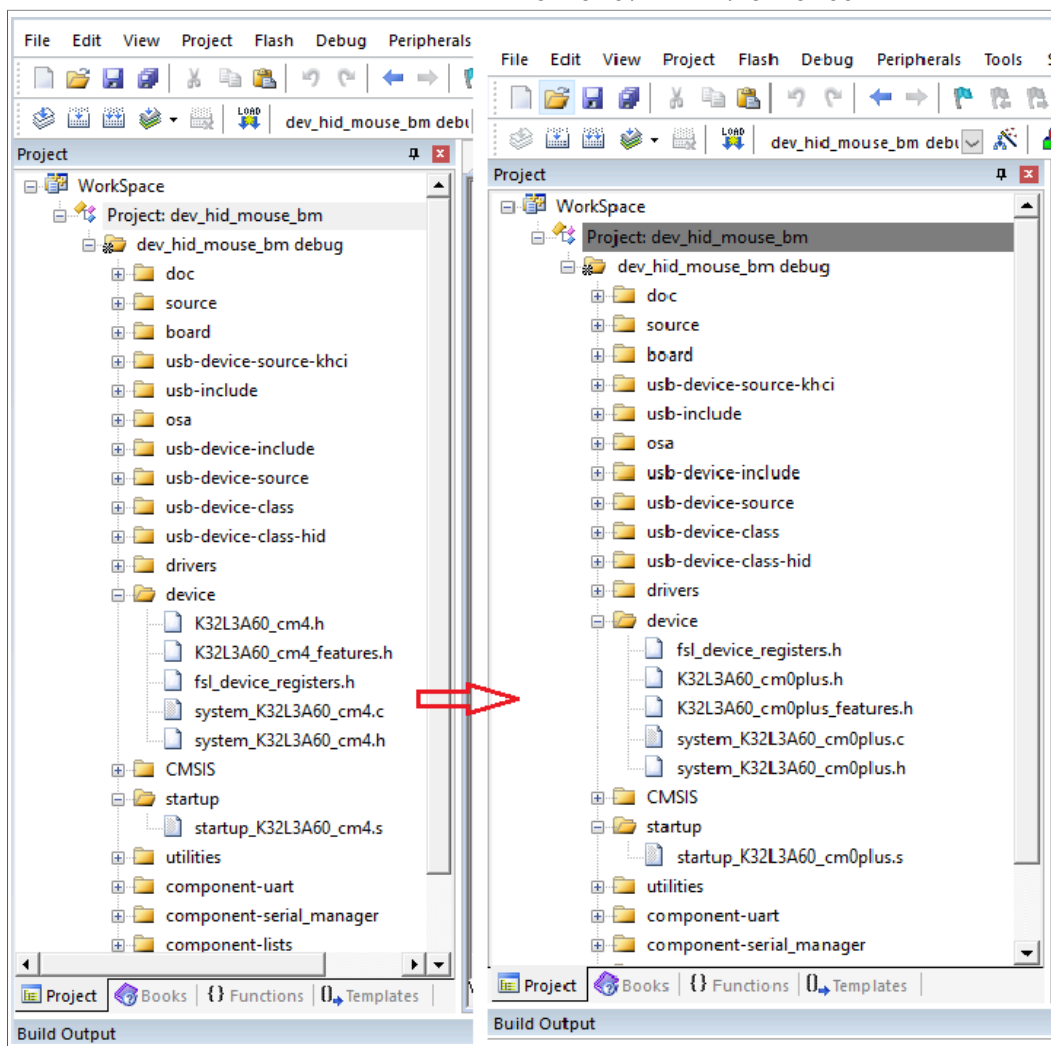
Update the include path:



After the above project configuration is complete, the m4 USB example project would be changed to M0p project. M0p example USB project can now be downloaded and debugged.

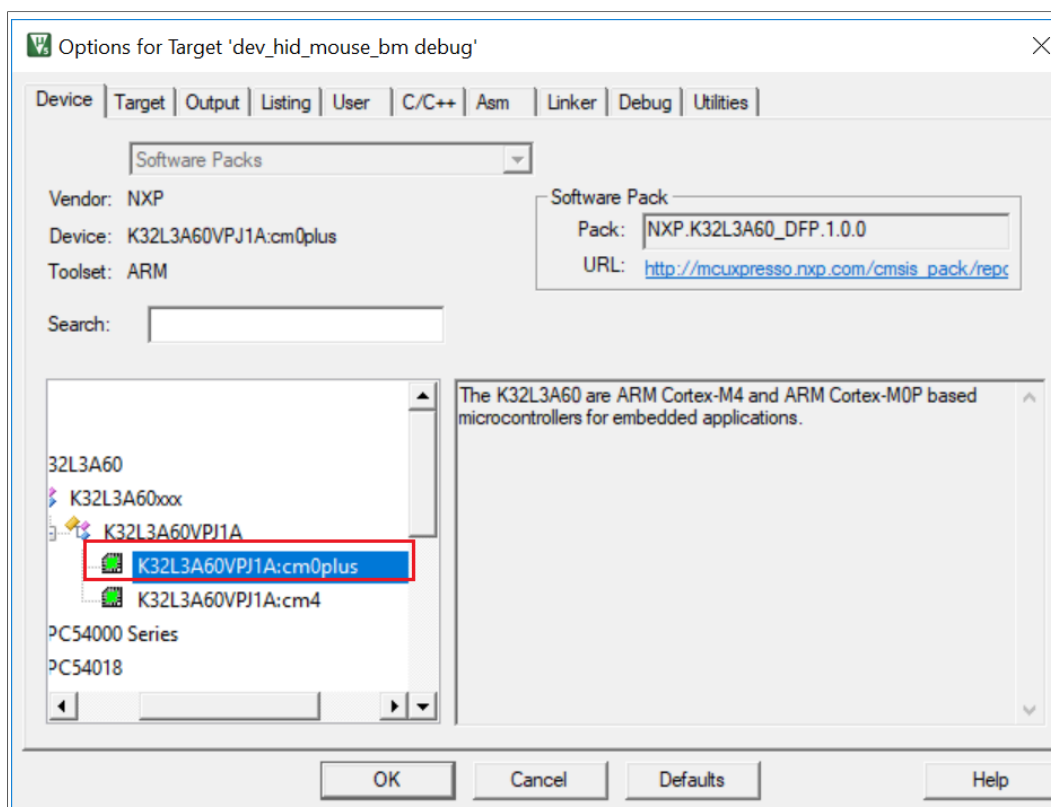
### 3 MDK

1. Change startup and system file from M4 platform files to M0p platform files. The below picture shows how to change m4 project files to M0p project file. The files are available in folder: FRDM-K32L3A6\devices\K32L3A60



2. Open M4 project in MDK, in option > Device, change the CPU type form M4 to M0p.

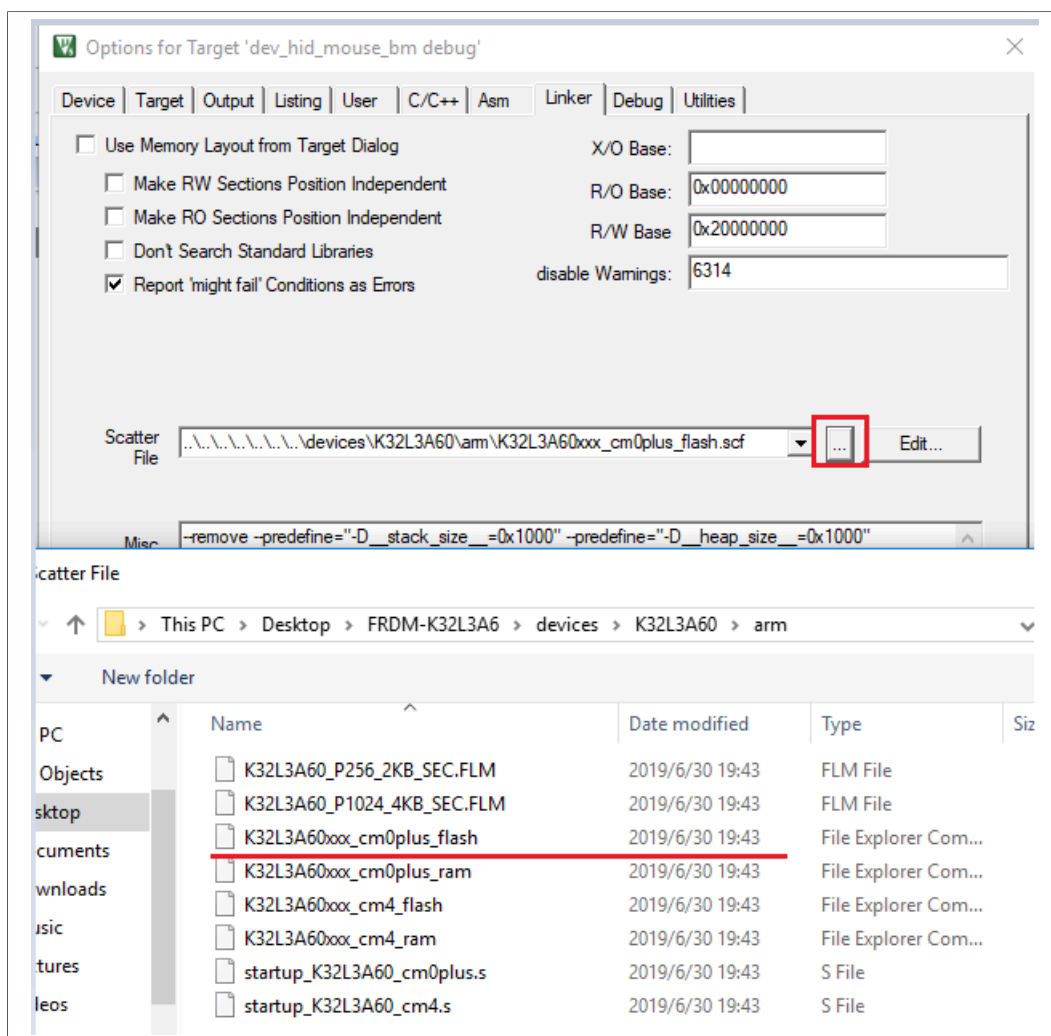
## Steps to migrate from M4 USB project to M0p USB example project for K32



3. Again in M4 project in MDK, in option-->linker, change the linker configure file form M4 link file to M0p link file. The linker file path is devices\K32L3A60 folder.

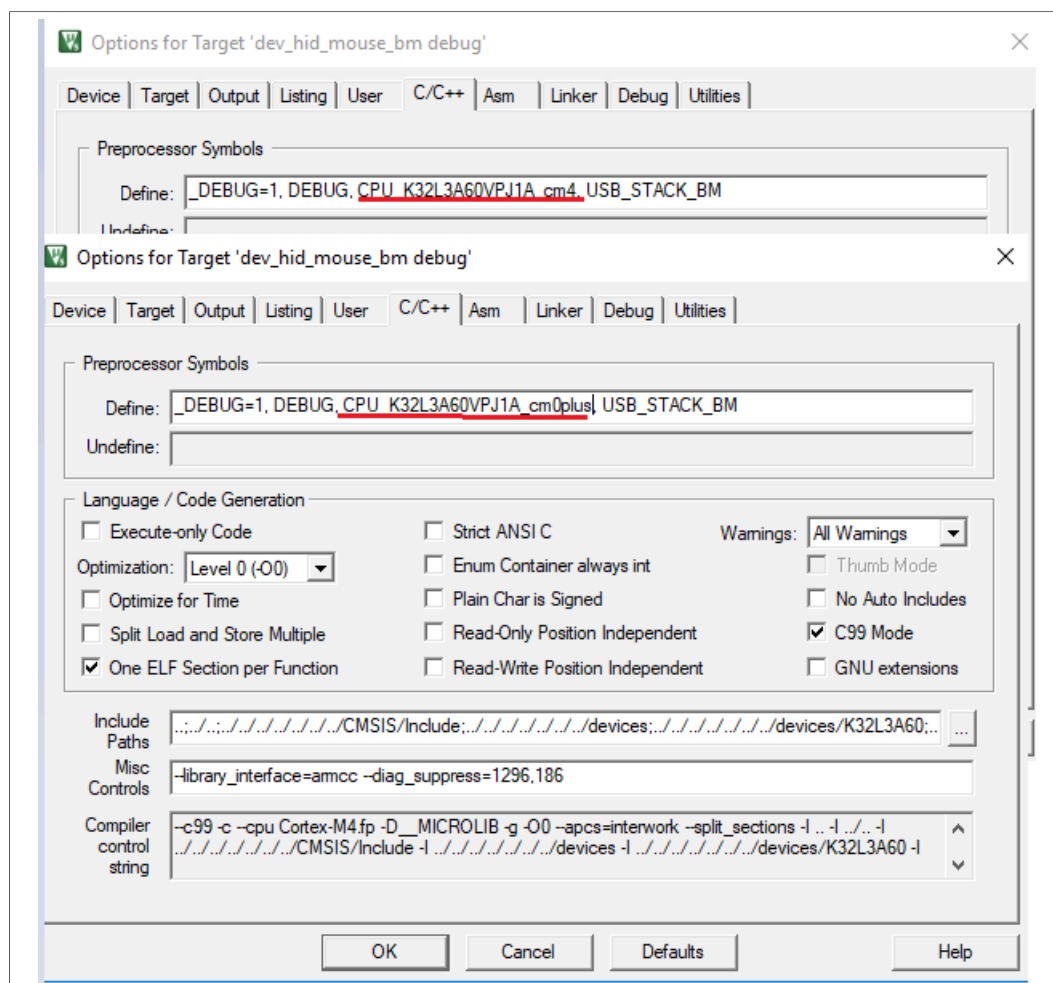


## Steps to migrate from M4 USB project to M0p USB example project for K32



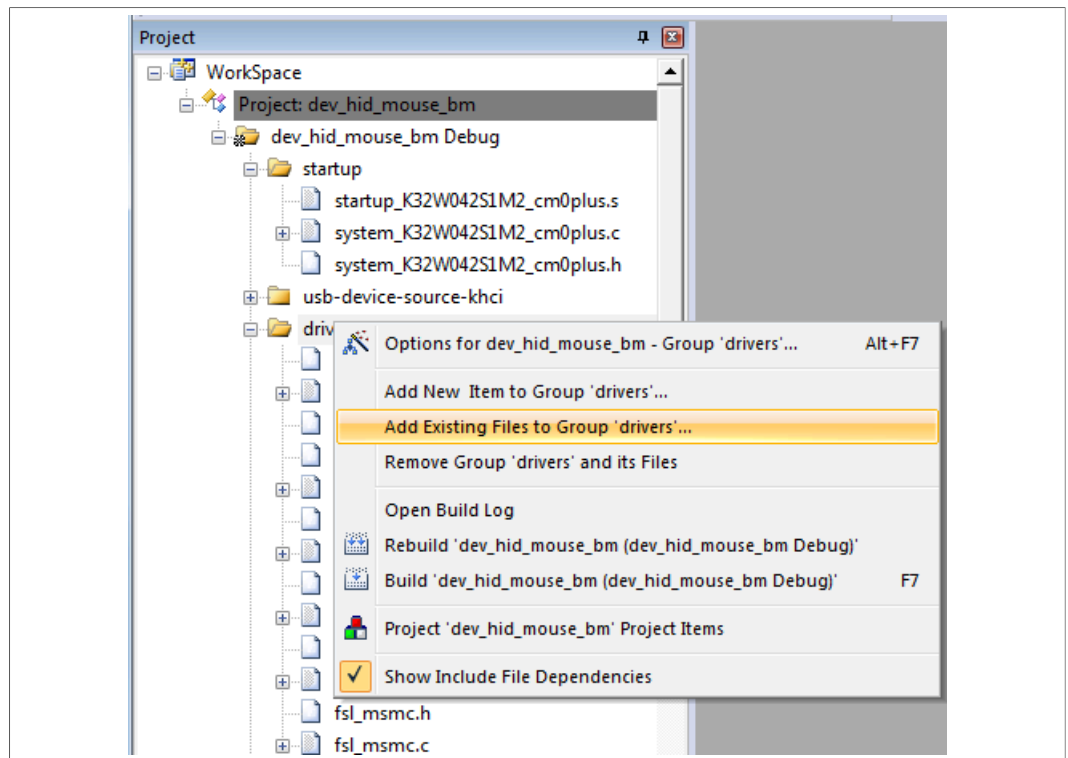
- In M4 project in MDK, in option > C/C++ compiler, change the CPU MACRO from "CPU\_K32L3A60VPJ1A\_cm4" to "CPU\_K32L3A60VPJ1A\_cm0plus".

## Steps to migrate from M4 USB project to M0p USB example project for K32

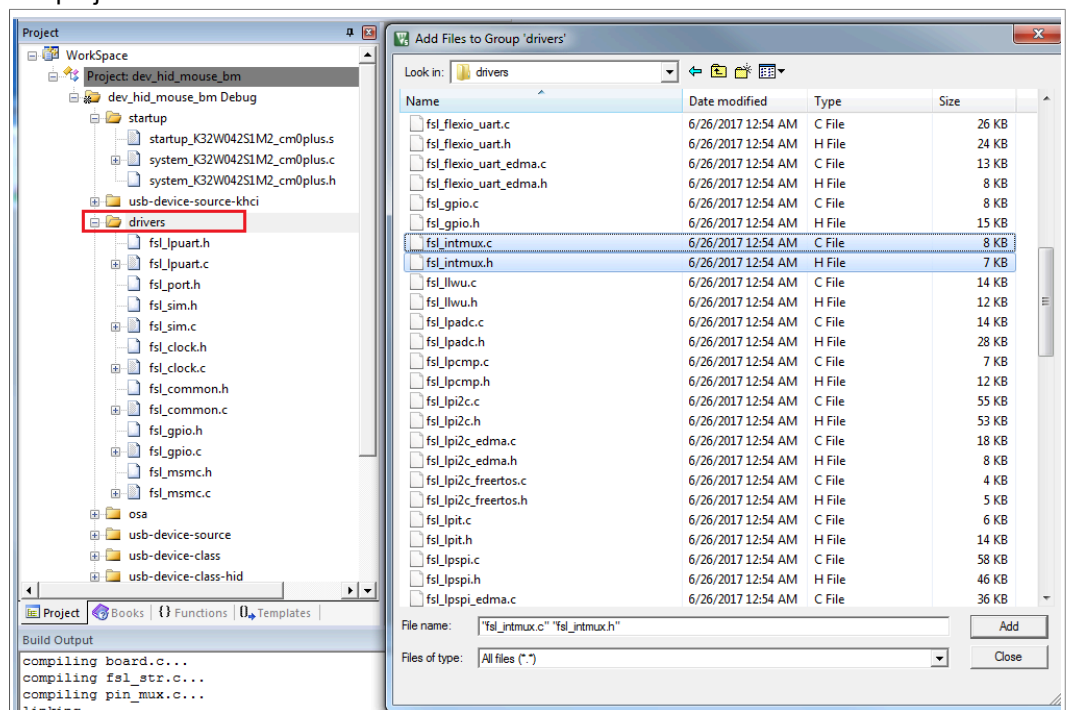


5. Add int-mux file to M0p project, driver -add Existing Files to Group 'driver', as shown in the image bellow

## Steps to migrate from M4 USB project to M0p USB example project for K32

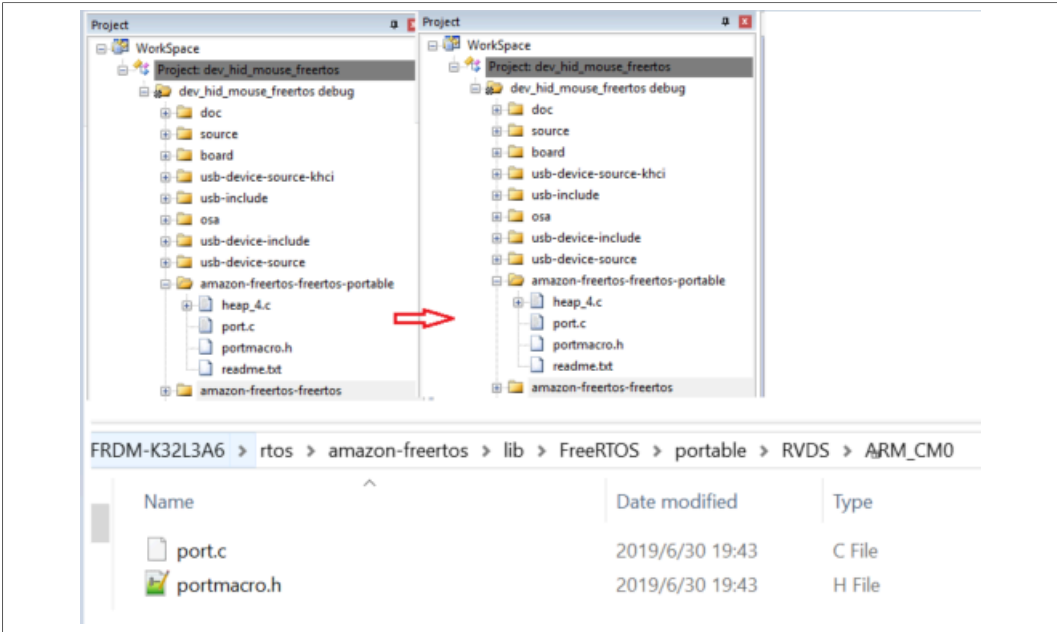


6. Add FRDM-K32L3A6\devices\K32L3A60\drivers\fsl\_intmux.c and fsl\_intmux.h files to project.

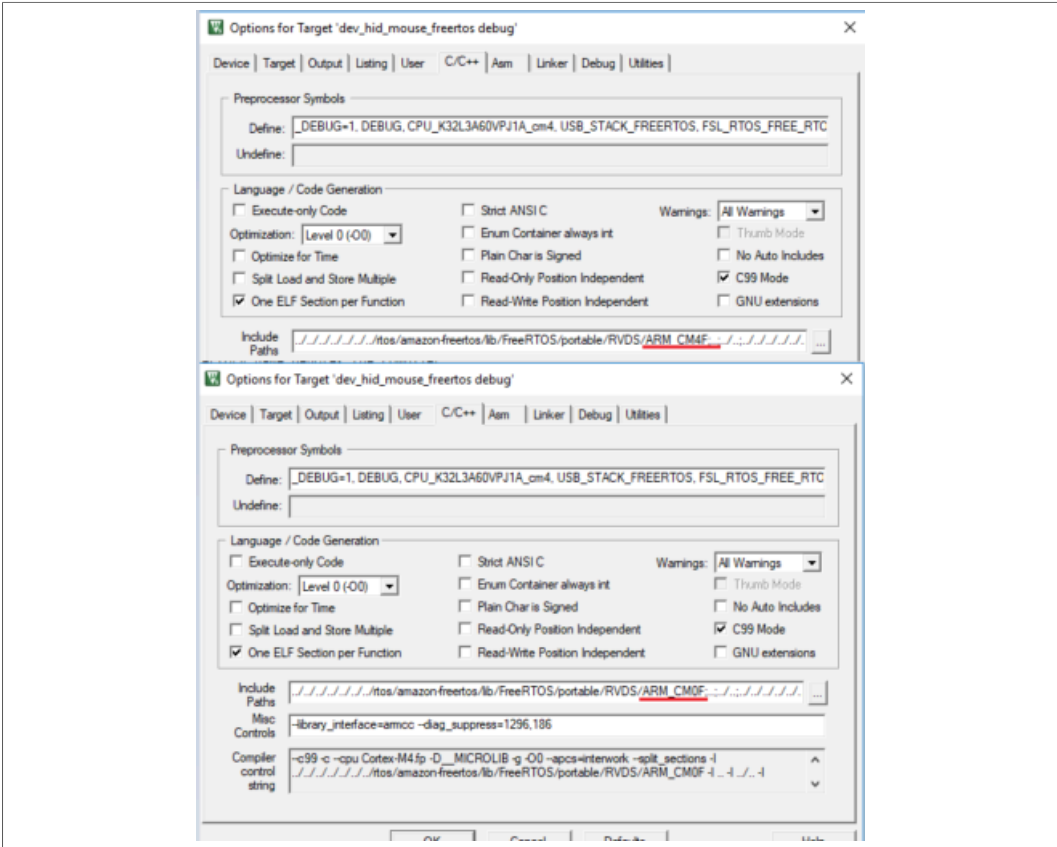


7. For freertos example. Update the freertos related portable file and include path from M4 to M0.

Steps to migrate from M4 USB project to M0p USB example project for K32



Update the include path:

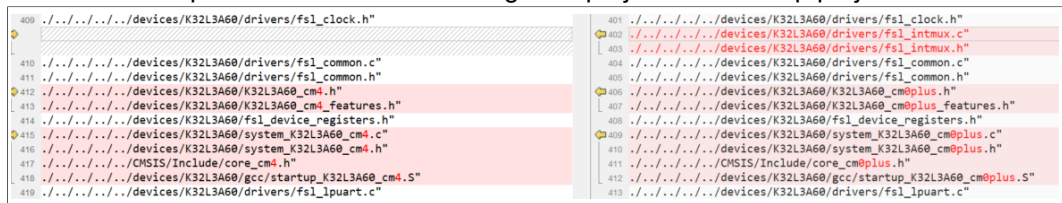


After the above project configuration is complete, the m4 USB example project would be changed to M0p project. M0p example USB project can now be downloaded and debugged.

## Steps to migrate from M4 USB project to M0p USB example project for K32

## 4 ARMGCC

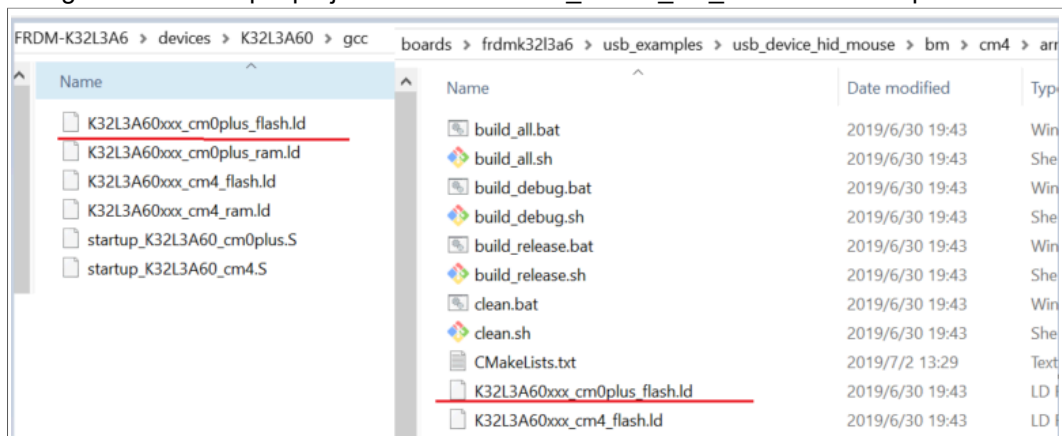
1. Update startup and system file from M4 platform files to M0p platform files.  
Open the CMakeLists.txt of the example, such as FRDM-K32L3A6\boards\frdmk32l3a6\usb\_examples\usb\_device\_hid\_mouse\bm\armgcc\ CMakeLists.txt  
The bellow picture shows how to change m4 project files to M0p project file.



2. Open CMakeLists.txt.  
Replace all the CPU setting from cortex-m4 to cortex-m0plus.  
Replace all the `"-mfloat-abi=hard"` to `"-mfloat-abi=soft"`  
Delete all `"mfpu=fpv4-sp-d16"`

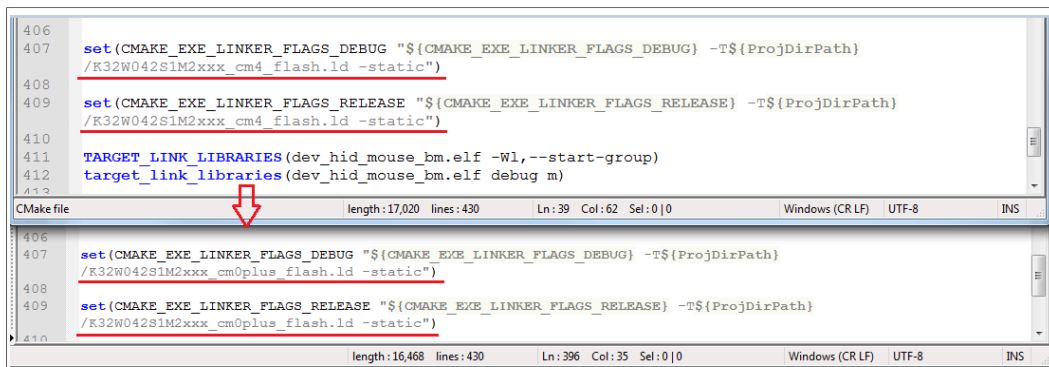


3. Change the linker configure file form M4 link file to M0p link file. The linker file path is devices\ K32L3A60 folder.  
Copy K32L3A60xxx\_cm0plus\_flash.ld from FRDM-K32L3A6 \devices\ K32L3A60 \gcc to the example project folder. Take usb\_device\_hid\_mouse as example.



4. Modify the CMakeLists.txt.

## Steps to migrate from M4 USB project to M0p USB example project for K32

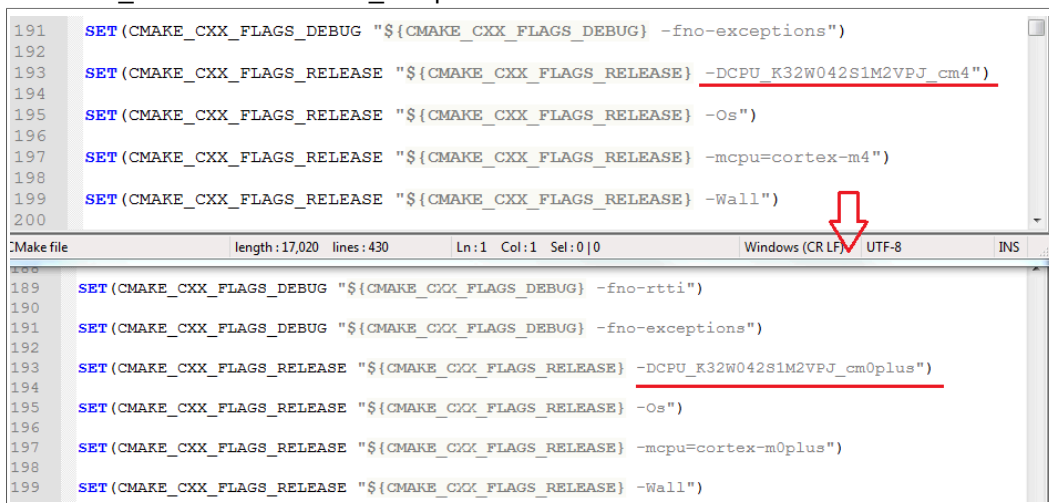


```

406 set(CMAKE_EXE_LINKER_FLAGS_DEBUG "${CMAKE_EXE_LINKER_FLAGS_DEBUG} -T${ProjDirPath}
407 /K32W042S1M2xxx_cm4_flash.ld -static")
408
409 set(CMAKE_EXE_LINKER_FLAGS_RELEASE "${CMAKE_EXE_LINKER_FLAGS_RELEASE} -T${ProjDirPath}
410 /K32W042S1M2xxx_cm4_flash.ld -static")
411
412 TARGET_LINK_LIBRARIES(dev_hid_mouse_bm.elf -Wl,--start-group)
413 target_link_libraries(dev_hid_mouse_bm.elf debug m)

```

5. Change all the CPU MACRO from "CPU\_K32W042S1M2VPJ\_cm4" to "CPU\_K32W042S1M2VPJ\_cm0plus" in CMakeLists.txt.

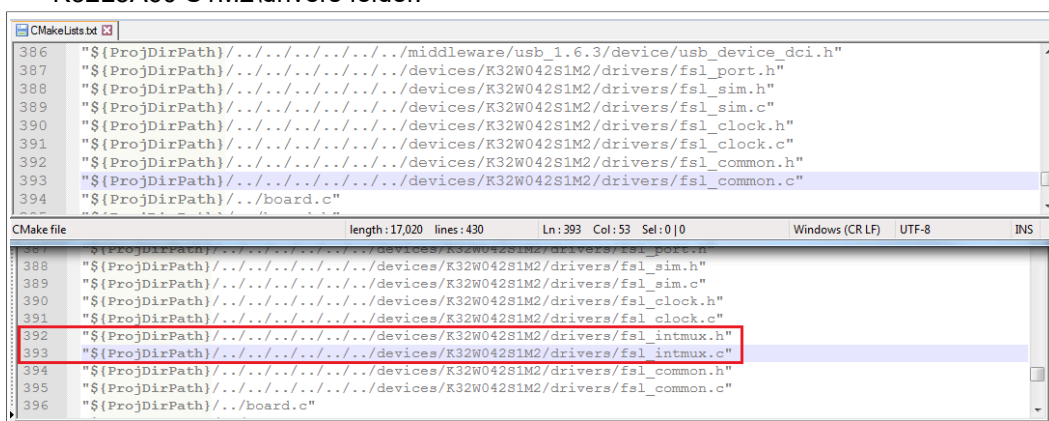


```

191 SET(CMAKE_CXX_FLAGS_DEBUG "${CMAKE_CXX_FLAGS_DEBUG} -fno-exceptions")
192
193 SET(CMAKE_CXX_FLAGS_RELEASE "${CMAKE_CXX_FLAGS_RELEASE} -DCPU_K32W042S1M2VPJ_cm4")
194
195 SET(CMAKE_CXX_FLAGS_RELEASE "${CMAKE_CXX_FLAGS_RELEASE} -Os")
196
197 SET(CMAKE_CXX_FLAGS_RELEASE "${CMAKE_CXX_FLAGS_RELEASE} -mcpu=cortex-m4")
198
199 SET(CMAKE_CXX_FLAGS_RELEASE "${CMAKE_CXX_FLAGS_RELEASE} -Wall")
200

```

6. Add int-mux file to M0p project, as bellow  
Add FRDM-K32L3A6 \devices\K32W042 K32L3A60 S1M2\drivers\fs1\_intmux.c and fs1\_intmux.h files to project.
7. Check the fs1\_intmux.c/ fs1\_intmux.h is in FRDM-K32L3A6 \devices\K32W042 K32L3A60 S1M2\drivers folder.



```

386 "${ProjDirPath}/../../../../../../middleware/usb_1.6.3/device/usb_device_dci.h"
387 "${ProjDirPath}/../../../../../../devices/K32W042S1M2/drivers/fs1_port.h"
388 "${ProjDirPath}/../../../../../../devices/K32W042S1M2/drivers/fs1_sim.h"
389 "${ProjDirPath}/../../../../../../devices/K32W042S1M2/drivers/fs1_sim.c"
390 "${ProjDirPath}/../../../../../../devices/K32W042S1M2/drivers/fs1_clock.h"
391 "${ProjDirPath}/../../../../../../devices/K32W042S1M2/drivers/fs1_clock.c"
392 "${ProjDirPath}/../../../../../../devices/K32W042S1M2/drivers/fs1_common.h"
393 "${ProjDirPath}/../../../../../../devices/K32W042S1M2/drivers/fs1_common.c"
394 "${ProjDirPath}/../board.c"

```

8. For freertos example. Update the freertos related portable file and include path from M4 to M0.  
Change all the source path and include path "Source/portable/GCC/ARM\_CM4F" to "Source/portable/GCC/ARM\_CM0",

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```
360 include_directories(${ProjDirPath}/../rtos/amazon-freertos/lib/FreeRTOS/portable/GCC/ARM_CM0)
361 include_directories(${ProjDirPath}/../rtos/amazon-freertos/lib/FreeRTOS/portable/GCC/ARM_CM4F)

CMake file length: 22,738 lines: 527 Ln: 361 Col: 110 Sel: 6|1 Windows (CR LF)
361 include_directories(${ProjDirPath}/../rtos/amazon-freertos/lib/FreeRTOS/portable/GCC/ARM_CM4F)
362

"${ProjDirPath}/../rtos/amazon-freertos/lib/FreeRTOS/portable/GCC/ARM_CM4F/port.c"
"${ProjDirPath}/../rtos/amazon-freertos/lib/FreeRTOS/portable/GCC/ARM_CM4F/portmacro.h"
"${ProjDirPath}/../rtos/amazon-freertos/lib/FreeRTOS/queue.c"
"${ProjDirPath}/../rtos/amazon-freertos/lib/FreeRTOS/stream_buffer.c"
"${ProjDirPath}/../rtos/amazon-freertos/lib/FreeRTOS/tasks.c"
"${ProjDirPath}/../rtos/amazon-freertos/lib/FreeRTOS/timers.c"

length: 22,741 lines: 527 Ln: 415 Col: 72 Sel: 0|0 V
"${ProjDirPath}/../rtos/amazon-freertos/lib/FreeRTOS/portable/GCC/ARM_CM0/port.c"
"${ProjDirPath}/../rtos/amazon-freertos/lib/FreeRTOS/portable/GCC/ARM_CM0/portmacro.h"
```

After the above project configuration is complete, the m4 USB example project would be changed to M0p project. M0p example USB project can now be downloaded and debugged.

5 Revision history

This table summarizes revisions to this document.

Table 1. Revision history

Revision number	Date	Substantive changes
0	20 March 2020	Initial release
1	11 July 2022	Editorial and layout updates.



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